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Dimensions	
D	25.64mm +/-0.635mm
L	1.4mm +/-0.127mm
H	2.54mm NOM
F	1.778mm +/-0.25mm
A	10.67mm MAX
B	12.702mm MAX
C	11.43mm +/-0.635mm
E	13.7mm +/-0.89mm
K	0.5mm NOM

Packaging Specifications	
Packaging	Waffle, Box
Packaging Quantity	16

General Information	
Series	KPS-MCC Indust COG HT200C
Style	Leaded Stacked Chip
Description	Low ESR, Stacked Ceramic Chips
Features	200C, Low ESR, High Thermal Stability, Bulk Capacitance
RoHS	With Exemptions
REACH	SVHC (Pb – CAS 7439-92-1)
SCIP Number	297427bb-2a48-4853-b594-641304a2cc24
Termination	Silver
Lead	L Leads
AEC-Q200	No
Notes	Number of chips in this stack: 8.

Specifications	
Capacitance	1 uF
Capacitance Tolerance	10%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	819 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Dissipation Factor	0.1% 1 kHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	1 GOhms

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